



**FOR IMMEDIATE RELEASE**

**EV GROUP INTRODUCES NEW EVG610 MASK AND BOND ALIGNER OPTIMIZED FOR GREATER COST AND PROCESS FLEXIBILITY**

***New System Provides World-class Alignment Technology at an Affordable Cost***

**ST. FLORIAN, AUSTRIA, July 6, 2010** – [EV Group \(EVG\)](#), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced that it has introduced the EVG610 mask and bond aligner, specifically to address its university and research customers' demands for a lower costing system with greater process versatility. Complementing the [EVG501 R&D wafer bonder launched a year ago](#), the EVG610 is specifically designed to provide wider access to EVG's core alignment technology platform used throughout its latest mask and bond aligner systems. Designed to offer the flexibility of its industry-proven [EVG620 automated mask and bond aligner](#), which is targeted for volume production, the EVG610 eliminates costly features, such as automation, which may not be needed in a research facility.

EVG executive technology director, Paul Lindner, commented, "EV Group has been working with research facilities for 30 years, giving us insight into the unique requirements of smaller-scale university research and production facilities. That is why we continue to roll out products like the EVG610 to make sure that students and first-time users have access to affordable systems with superior technology features that may not otherwise be available in lower-cost models. This latest addition is an integral part of our mask aligner and bond aligner product families, and completes our portfolio spanning the entire manufacturing chain—from R&D all the way to full-scale, high-volume production environments."

Facing greater budget constraints, universities and research institutions are compelled to purchase equipment with more flexibility that will enable them to scale processes across multiple research projects and applications. Cost and system flexibility—without sacrificing quality results—are key factors in their decision-making processes. EVG's new, lower-cost system provides mask alignment technology with the highest overlay accuracy enabling the best possible exposure, while its bond alignment capability offers alignment accuracy that maximizes process windows—both ensuring higher yields. What's more, the EVG610 enables researchers to seamlessly migrate their processes to volume production environments.

**EVG610 R&D System Features**

The EVG610 mask and bond alignment system is a highly flexible R&D system that can process substrate pieces and wafers up to 200 mm. This mask and bond aligner system is designed to support a wide variety of processes such as UV-nanoimprint lithography (UV-NIL) and fine patterning, wafer bumping and chip-scale packaging for MEMS, integrated circuit and compound semiconductor devices.

The EVG610 system offers core technologies from EVG's high-volume mask and bond alignment systems including:

- Option to combine mask and bond alignment capabilities optimizes total cost of ownership (TCO)—reduces investment, footprint and operation cost compared to two separate systems
- Flexible configurations available from pieces up to 4-, 6- or 8-inch substrates
- Bottom-side alignment capability, supporting back side lithography and bond alignment processes
- Unmatched exposure light uniformity at wafer level (down to  $\pm 1.5$  percent)
- Processes are fully compatible to EVG production mask and alignment bonding systems
- Flexible multi-user system with multi-language capability
- Maintenance-free and high-precision monolithic air bearing stage
- Windows®-based user interface

The EVG610 is available for purchase immediately. For more information or to learn more about the EVG610 and other EVG mask and bond alignment systems please visit [www.evgroup.com](http://www.evgroup.com).

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**About EV Group**

EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for major ICs and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. The company's unique Triple i-approach (invent - innovate - implement) is supported by a vertical integration, allowing EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. More information is available at [www.EVGroup.com](http://www.EVGroup.com).

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